



## Pin Function

Pin Name	Pin#	Function
VIN	1	This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching current needed by regulator.
Output	2	Internal switch. The voltage at this pin switches between (+VIN - VSAT) and approximately -0.5V, with a duty cycle of approximately VOUT/VIN. To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be kept to a minimum.
Ground	3	Circuit ground
Feedback(FB)	4	Senses the regulated output voltage to complete the feedback loop.
ON/OFF(SD)	5	Allows the switching regulator circuit to be shutdown using logic level signals. Thus drop the total input supply current to approximately 150µA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 18V) shuts the regulator down. If this shutdown feature is not needed, ON/OFF pin can be wired to the ground pin.

## Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Supply Voltage	VCC	24	V
ON/OFF Pin Input Voltage	VSD	-0.3 ~ +18	V
Feedback Pin Voltage	VFB	-0.3 ~ +18	V
Output Voltage to ground	VOUT	-1	V
Power Dissipation	PD	Internally Limited	W
Storage Temperature	TST	-65 ~ +150	°C
Operating temperature	TOP	-40 ~ +125	°C
Operating Voltage	VOP	+4.5 ~ +22	V

## S5U2596M Electrical Characteristics

Specifications in **boldface type** are for **full operating temperature range**. The other type are for TJ=25 °C.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Feedback	VFB	5 ≤ VIN ≤ 22V, 0.2A ≤ ILOAD ≤ 3A VOUT=3V	1.193/ <b>1.180</b>	1.230	1.267/ <b>1.280</b>	V
Efficiency	η	VIN=12V, ILOAD=3A, VOUT=3V		74		%

## S5U2596M-33 Electrical Characteristics

Specifications in **boldface type** are for **full operating temperature range**. The other type are for TJ=25 °C.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Feedback	VFB	5.5V ≤ VIN ≤ 22V 0.2A ≤ ILOAD ≤ 3A	3.168/ <b>3.135</b>	3.3	3.432/ <b>3.465</b>	V
Efficiency	η	VIN=12V, ILOAD=3A		75		%

## S5U2596M-50 Electrical Characteristics

Specifications in **boldface type** are for **full operating temperature range**. The other type are for TJ=25 °C.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Feedback	VFB	8V ≤ VIN ≤ 22V 0.2A ≤ ILOAD ≤ 3A	4.80/ <b>4.75</b>	5.0	5.20/ <b>5.25</b>	V
Efficiency	η	VIN=12V, ILOAD=3A		80		%

## S5U2596M-12 Electrical Characteristics

Specifications in **boldface type** are for **full operating temperature range**. The other type are for TJ=25 °C.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Feedback	VFB	15V ≤ VIN ≤ 22V 0.2A ≤ ILOAD ≤ 3A	11.52/ <b>11.40</b>	12	12.48/ <b>12.60</b>	V
Efficiency	η	VIN=16V, ILOAD=3A		89		%

## All Output Voltage Version Electrical Characteristics

Specifications in **boldface type** are for **full operating temperature range**. The other type are for  $T_J=25\text{ }^{\circ}\text{C}$ .

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Feedback bias current	IFB	VFB=1.3V (adjustable version only)	-	-10	<b>-50/-100</b>	nA
Oscillator frequency	FOSC		<b>127/110</b>	150	<b>173/173</b>	kHz
Oscillator frequency of short circuit protect	FSCP	When current limit occurred and VFB<0.5V, $T_A=25\text{ }^{\circ}\text{C}$ .	5	15	25	kHz
Saturation voltage	VSAT	ILOAD=3A No outside circuit VFB=0V force drive on	-	1.4	<b>1.6/1.7</b>	V
Max. duty cycle (ON)	DC	VFB=0V force drive on	-	100	-	%
Max. duty cycle (OFF)		VFB=12V force drive off	-	0	-	
Current limit	ICL	Peak current No outside circuit VFB=0V force drive on	3.6	4.5	<b>5.5/6.5</b>	A
Output leakage current	IL	Output=0V, No outside circuit VFB=12V force drive off	-	-	-200	$\mu\text{A}$
		Output=-1V, $V_{IN}=22\text{V}$	-	-5	-	mA
Quiescent current	IQ	VFB=12V force drive off	-	5	10	mA
ON/OFF pin logic input	VIL	Low (Regulator ON)	-	-	0.6	V
Threshold Voltage	VIH	High (Regulator OFF)	2.0	-	-	
ON/OFF pin Logic input current	IH	VLOGIC=2.5V ( Regulator OFF)	-	-	-0.01	$\mu\text{A}$
ON/OFF pin input current	IL	VLOGIC=0.5V ( Regulator ON)	-	-0.1	-1	
Standby quiescent current	ISTBY	ON/OFF pin=5V, $V_{IN}=12\text{V}$	-	150	200	$\mu\text{A}$
Thermal Resistance	$\theta_{JC}$	Junction to Case	-	3.5	-	$^{\circ}\text{C/W}$
	$\theta_{JA}$	Junction to Ambient with copper area of approximately 3 in <sup>2</sup>	-	23	-	

Unless otherwise specified,  $V_{IN}=12\text{V}$  for 3.3V, 5V, adjustable version and  $V_{IN}=18\text{V}$  for the 12V version. ILOAD=0.5A

## Function Description

The TO-263 surface mount package tab was designed to be soldering to the copper on printed circuit board. The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PC board copper area that the package is soldered to should be at least 0.8in<sup>2</sup>, and ideally should have 2 or more square inches of 2 oz. Additional copper area improves the thermal characteristics, but with copper area greater than approximately 6in<sup>2</sup>, only small improvements in heat dissipation are realized. If further thermal improvements are needed, double sided, multi-layer PC board with large copper areas and/or airflow will be recommended.

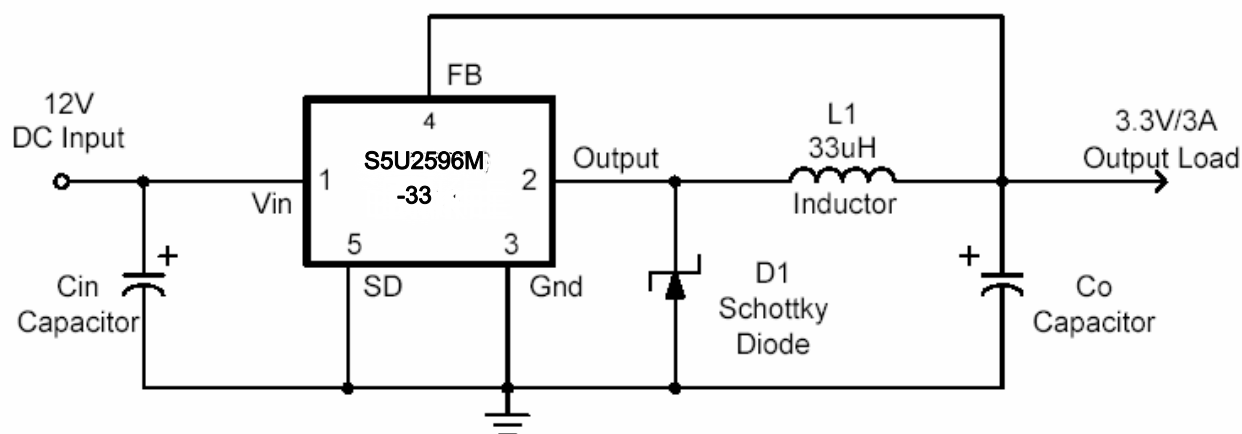
The S5U2596M junction temperature rises above ambient temperature with a 2A load for various input and output voltages. This data was taken with the circuit operating as a buck-switching regulator with all components mounted on a PC board to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but be aware that there are many factors that can affect the junction temperature. When load current higher than 3A are used, double sided or multi-layer PC boards with larger copper areas and/or airflow might be needed, especially for high ambient temperatures and high output voltages.

For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout. (One exception to this is the output (switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

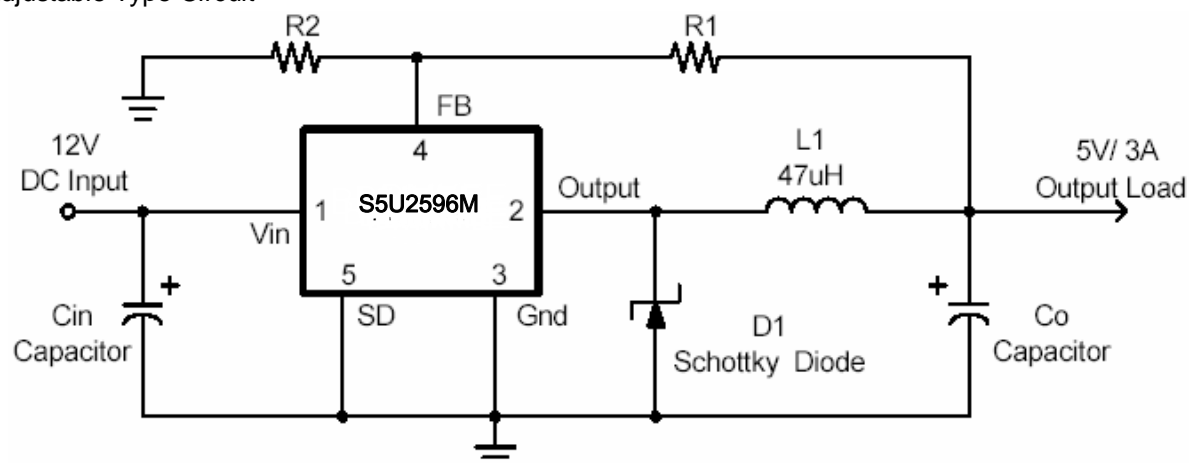
Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors will affect these numbers. Some of these factors include board size, shape, thickness, position, location and even board temperature. Other factors are, trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.

## Typical Application Circuit

### (1) Fixed Type Circuit



### (2) Adjustable Type Circuit

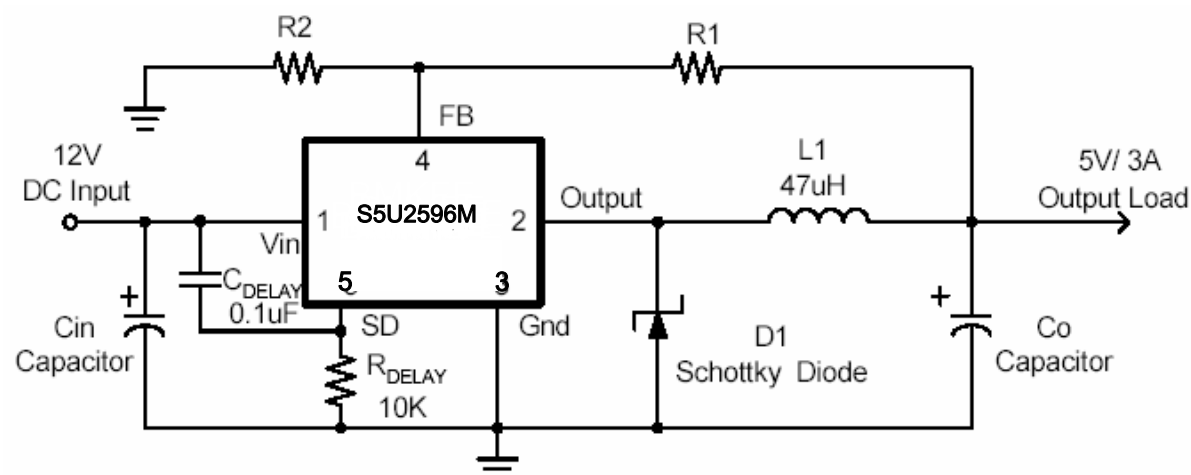


$$V_{out} = V_{FB} \times \left(1 + \frac{R1}{R2}\right)$$

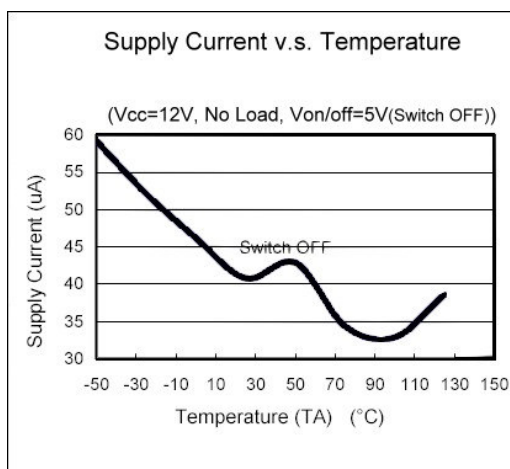
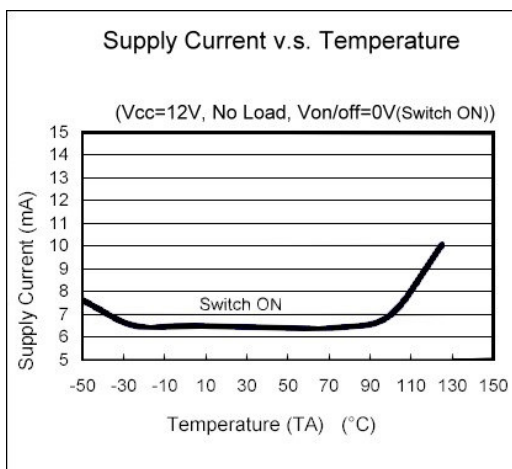
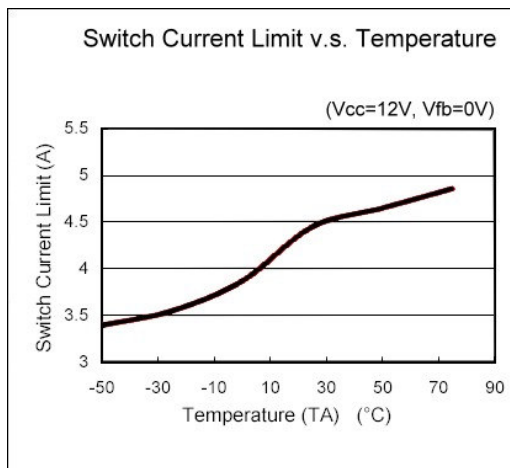
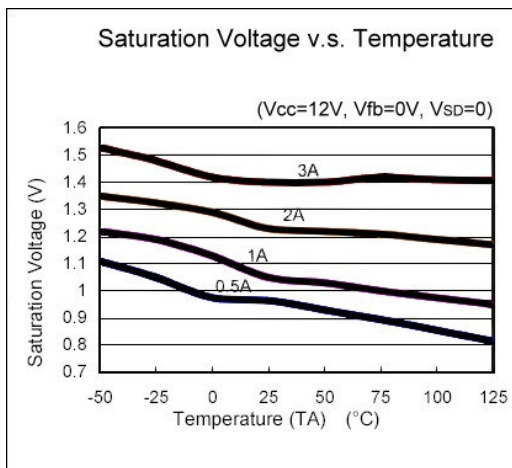
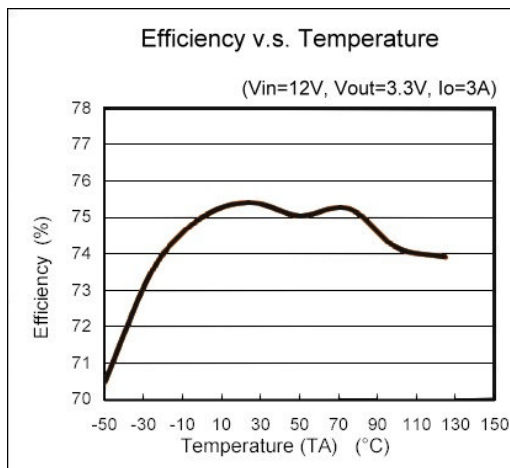
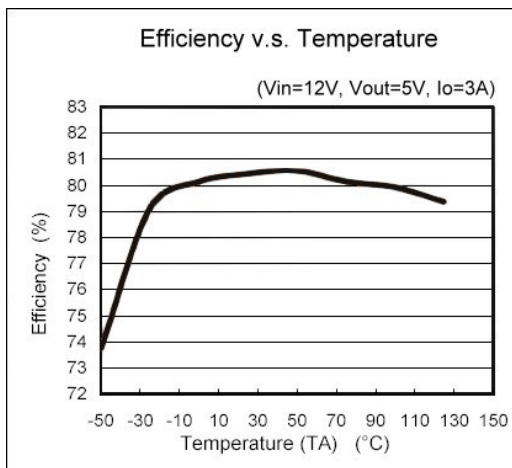
$$V_{FB} = 1.23V$$

$$R2 = 1K \sim 3K$$

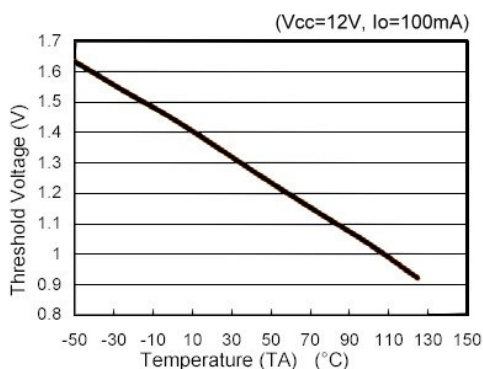
### (3) Delay Start Circuit



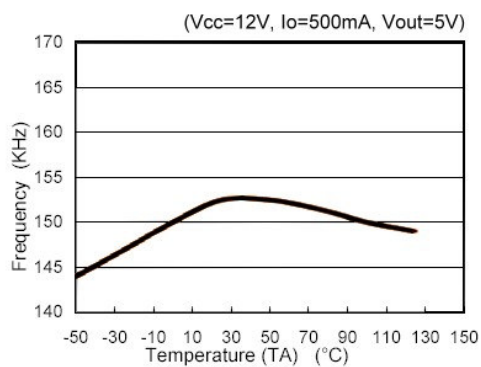
## Typical Performance Characteristics



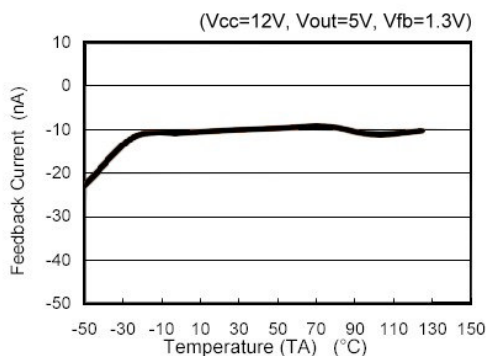
Threshold Voltage v.s. Temperature



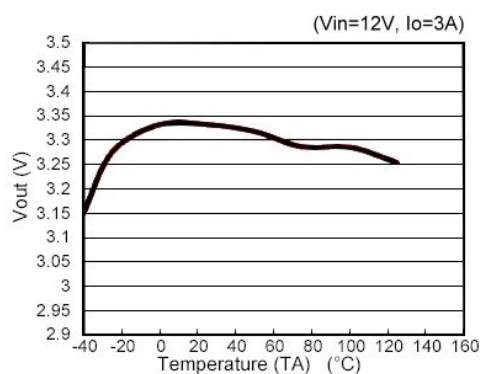
Frequency v.s. Temperature



Feedback Current v.s. Temperature



Output Voltage v.s. Temperature



ON/OFF Current v.s. ON/OFF Voltage

